

THMY

Testing the Next AI Wave

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THMY, scheduled to be listed on the ACE Market on 23 October, is a Malaysia-based provider of automated test solutions specialising in in-circuit (ICT) and functional circuit test (FCT) systems for the electronics and electrical (E&E) industry. The IPO price of RM0.31 implies a ~28% discount to both regional and local peers and ~41% discount to Malaysia-listed test and semiconductor equipment players, making it one of the cheapest listed exposures to AI hardware growth. The Group designs, develops, fabricates, and assembles customised test fixtures and platforms for leading EMS, industrial, and technology clients, enabling reliable validation of increasingly complex PCB assemblies. Riding on structural growth in AI hardware, hyperscaler infrastructure, and regional EMS expansion in Thailand, THMY is well-positioned to benefit from rising test complexity and higher-value engineering demand. We forecast revenue/PAT growth of 40%/48% in FY26 and 21%/26% in FY27, supported by margin expansion from a greater mix of high-complexity fixtures.

Riding on the AI Investment super-cycle. The global AI infrastructure boom shows no sign of slowing, with hyperscaler capex projected to reach USD376b and USD429b in FY26 and FY27, representing 24% and 14% YoY growth, respectively (see exhibit 3 for Kenanga estimates). This sustained investment wave is fuelling demand for advanced GPUs, ASICs, and high-density server boards — each requiring increasingly complex, multilayer designs that demand rigorous testing. THMY is riding on this AI hardware super-cycle, benefiting from the surge in test requirements across hyperscaler-linked production through its established EMS customers. While its AI-related exposure is still emerging, we estimate it will rise from the low single digits in FY25 to ~15%/20% of revenue in FY26/FY27. As board density and connection points continue to rise, THMY's expertise in customised, high-complexity test fixtures positions it squarely in the slipstream of long-term AI hardware expansion.

At the sweet spot of a growing industry. THMY operates in the automated test solutions (ATS) segment, a specialised, engineering-driven space that serves as a critical enabler for the electronics and semiconductor industries. Within Malaysia, THMY is among the largest homegrown providers of ICT and FCT solutions, while its key competitors are primarily regional players based in Taiwan, Singapore, and China. The company's ability to deliver fully customised, end-to-end test solutions from design and software development to fabrication and installation and it enjoys a competitive edge and strong customer stickiness (top three customers maintaining relationships for >10 years). As testing requirements rise in complexity and precision, THMY's niche positioning allows it to capture outsized value in a structurally expanding market.

Anchored by tier-1 EMS players with hyperscaler exposure. THMY's long-standing relationships with leading EMS, industrial, and technology manufacturers provide a resilient demand base and indirect exposure to hyperscaler-driven hardware cycles. These customers produce PCB assemblies and modules for AI, cloud, and datacentre systems, enabling steady order visibility and recurring project flow. Given the sustained hyperscaler capex growth and the aggressive ASIC development roadmaps ahead, we believe THMY is well-positioned to ride the next wave of AI hardware expansion through its established EMS customer base.

NOT RATED

IPO Price: RM0.31
Fair Value: RM0.60

Share Price Performance

KLCI	1,616.83
YTD KLCI chg	-1.5%

Post-IPO Major Shareholders

Ooi Can Nix	68.9%
Chew Yap Meng	1.3%

IPO proceeds (RM m)

Construction of new factory	25.9
Repayment of bank borrowings	5.2
Purchase of new machinery and equipment	3.7
D&D and R&D expenditure	1.9
Working capital	3.1
Estimated listing expenses	4.8
Total	44.6

Summary of IPO

Enlarged Share Cap (m)	888
IPO Price (RM)	0.31
Market Cap Upon Listing (RM m)	275.3
Shariah Complaint	Yes

Summary Earnings Table

FYE May (RM m)	2025A	2026F	2027F
Turnover	45.9	64.1	77.4
EBIT	10.4	17.3	23.2
PBT	10.6	17.0	22.9
Net Profit	10.0	14.8	18.7
Core Net Profit	10.0	14.8	18.7
Core EPS (sen)	1.1	1.7	2.1
Core EPS Growth (%)	49.0	47.7	25.8
NDPS (sen)	-	-	-
BVPS (RM)	0.0	0.1	0.1
Core PER (x)	27.4	18.6	14.8
PBV (x)	15.4	3.8	3.0
Net Gearing (x)	0.7	0.1	0.1
Net Div. Yield (%)	-	-	-

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NOT RATED with fair value of RM0.60. We assign a fair value of RM0.60 to THMY, based on 30x CY26F EPS, representing 20%–35% discount to both regional and local peers to reflect its smaller market capitalisation and relatively modest earnings base. Despite the discount, we believe the valuation is justified by THMY's strong structural growth outlook, underpinned by rising demand for complex, high-ASP fixtures, growing EMS exposure in Thailand, and indirect participation in hyperscaler-led AI hardware expansion. With margin expansion expected from a higher mix of engineering-intensive projects and planned capacity growth by 2QCY29, THMY offers attractive exposure to the AI-driven test automation cycle in ASEAN. The company commands premium pricing for its high-precision, custom-designed fixtures, which are critical to production yield and test accuracy, reinforcing its position as a high-value solutions provider rather than a volume-based manufacturer.

Risks to our calls include: (i) high customer concentration among major EMS clients, (ii) slower-than-expected adoption of high-complexity test solutions, and (iii) cyclical slowdown in global electronics and hyperscaler capex.

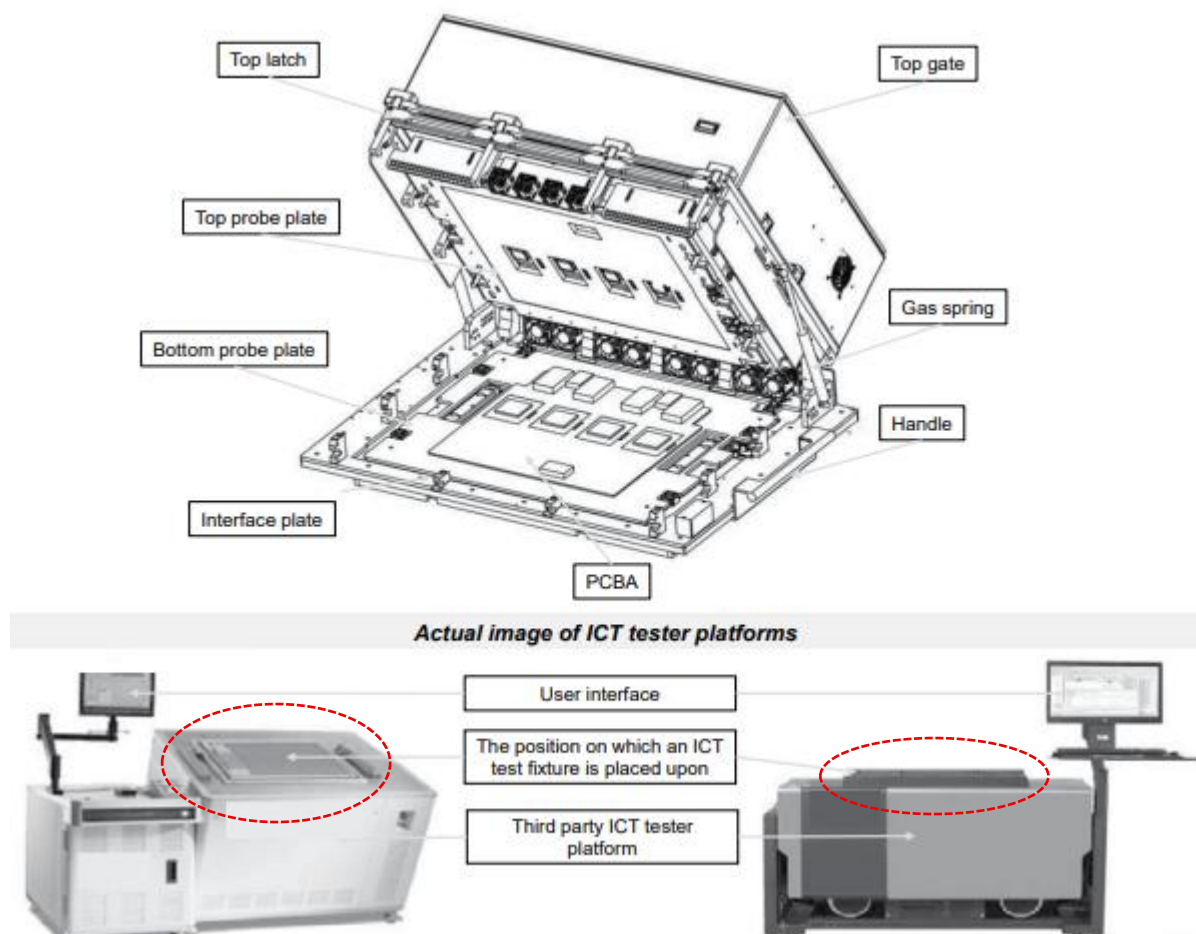
Company Overview

THMY Holdings Berhad ("THMY" or "the Group") is principally engaged in the provision of **automated test solutions** for the electrical and electronics (E&E) industry, with end-use applications across multiple sectors. The Group's core offerings encompass both **In-Circuit Test (ICT)** and **Functional Circuit Test (FCT)** solutions. THMY's value proposition lies in its ability to deliver end-to-end test solutions, covering the entire process from design and development through to fabrication, assembly, and on-site installation.

THMY is seeking to list on 23 Oct 2025 on the ACE market, involving an offer for sale new 144m shares, with the enlarged share base giving THMY a potential market capitalization of RM275.3m based on the offer price. Post IPO, THMY's key shareholders are expected to be Ooi Can Nix (68.9%) and Chew Yap Meng (1.3%)

Within its **Automated Test Solutions** segment, THMY operates across two key subsegments — **In-Circuit Test (ICT)** and **Functional Circuit Test (FCT)**.

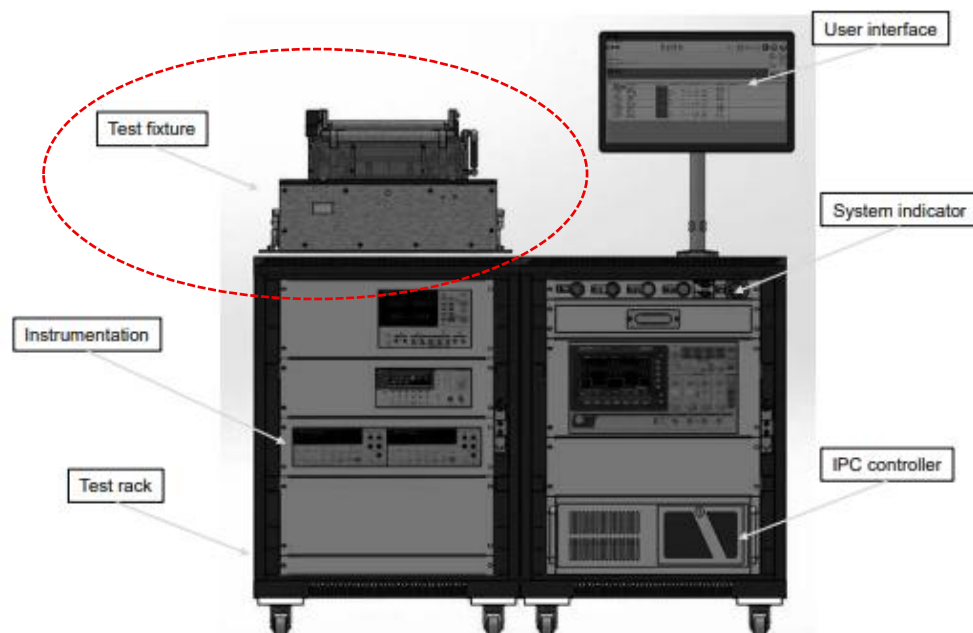
Exhibit 1: 3D Illustration of ICT Test Fixture



Source: Company Report, Kenanga Research

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In-Circuit Test (ICT). THMY provides ICT solutions through the design, development, fabrication, assembly, and installation of customised ICT test fixtures (see Exhibit 1) tailored to the specifications of customers' PCBAs, the type of ICT required, and the tester platforms in use. Precision customisation is essential to ensure probe positioning aligns with PCB test points, thereby delivering accurate and reliable results. While the Group does not fabricate ICT tester platforms, it leverages a wide range of industry-standard platforms supplied by global MNCs, and has invested in commonly used systems to guarantee compatibility and seamless integration with its proprietary software. This approach enables THMY to validate solutions directly on the same platforms as its customers, enhancing reliability and performance. By maintaining capabilities across various fixture types — including in-line, vacuum, pneumatic, and press-down test fixtures — the Group is able to support a broad customer base across diverse industries and geographies.

Exhibit 2: 3D Illustration of FCT test fixture

Source: Company Report, Kenanga Research

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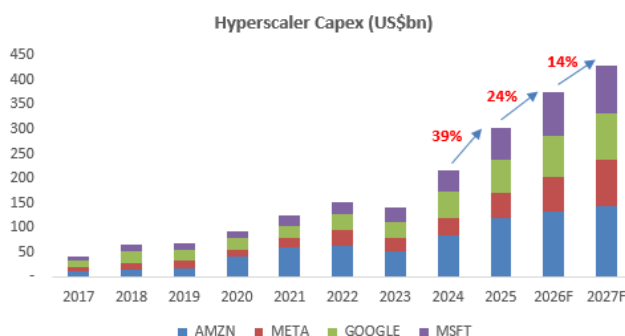
- **Functional Circuit Test (FCT).** THMY provides FCT solutions through the design, development, fabrication, assembly, and installation of both **test fixtures and tester platforms**, offering customers a complete turnkey solution. Each fixture is customised (see Exhibit 2) to align with the layout and design of customers' PCBAs, ensuring accurate functional validation. As FCT requirements vary significantly across applications, the Group also designs and fabricates the corresponding tester platforms, integrating them with its proprietary software to automate test execution and reporting. By delivering the fixture and platform as a unified system, THMY enables customers to comprehensively evaluate circuit performance, reliability, and compliance under simulated operating conditions.

Key Management

1. **Ooi Can Nix (Executive Director/ CEO)** is the Promoter, substantial shareholder, and Chief Executive Officer of THMY Holdings Berhad, appointed to the Board on 16 July 2024. A graduate in Physics from Universiti Kebangsaan Malaysia (2000), he began his career with Soletron Technology Sdn Bhd in 2001, progressing to Senior Staff Engineer before joining Plexus Manufacturing Sdn Bhd in 2006 as Unit Manager, where he managed test development and established the company's development centre in Penang. In 2007, he assisted Testing House Inc. in setting up its Southeast Asia office and subsequently co-founded Testing House Malaysia Sdn Bhd (now THMY Tech) in 2008, where he initially served as General Manager before being promoted to CEO in 2024. His past directorships include non-executive roles in NationGate Holdings Berhad (2021) and I-Testnology Sdn Bhd (2021–2024).
2. **Chew Yap Meng (Chief Operating Officer)** is the Executive Director of THMY Holdings Berhad, appointed to the Board on 31 January 2025. He holds a Diploma in Electrical & Electronic Engineering from Linton College (1998) and began his career with NatSteel Electronics (M) Sdn Bhd in 1999 as a technician supporting ICT and FCT production lines. In 2000, he joined Universal Instruments (Malaysia) Sdn Bhd as Field Support Engineer, later rising to Sales Manager, where he was responsible for ICT- and probe-related sales until 2016. He then joined THMY as Sales Manager, was redesignated as Operations Manager in 2017, and promoted to Senior Operations Manager in 2021 and Director of Operations in 2023. In 2024, he assumed the role of COO, overseeing daily operations and executing business development strategies, a position he continues to hold today.
3. **Yap Hooi Min (Financial Controller)** is tasked to oversee accounting, reporting, budgeting, taxation, and cash flow. She holds a Bachelor of Accounting from Universiti Utara Malaysia (2009) and has been a member of the Malaysian Institute of Accountants since 2013. Yap has over 16 years of experience spanning tax, audit, and financial management, having held roles at SH Tax Services, LLTC (now CHI-LLTC), TNL Partners PLT, and Edeltec Holdings Berhad, where she also served as Financial Controller before joining THMY in 2024.

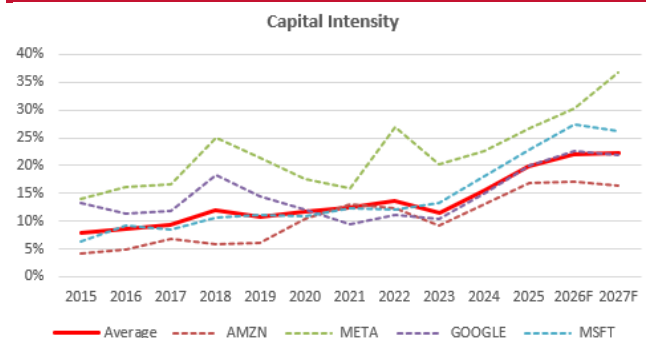
Demand Analysis

Exhibit 3: Hyperscaler CAPEX To Rise +39% in 2025, +24%/+14% In 2026/27F To USD376b/USD429b



Source: Bloomberg, Kenanga Research

Exhibit 4: Capital Intensity to Climb Toward ~22% In FY26–27



Source: Bloomberg, Kenanga Research

Sustained Acceleration in AI Infrastructure Spending. AI infrastructure investment continues to accelerate globally, with leading hyperscalers reporting stronger-than-expected capital expenditure through 2QCY25 and raising forward guidance amid intensifying AI adoption. Aggregate capex among major data-centre operators surged ~80% YoY, lifting capital intensity to around 20% of revenue — the highest level since the onset of the AI upcycle (see Exhibit 4). Looking ahead, hyperscaler capex is forecast to reach USD376b and USD429b in FY26 and FY27F, translating to +24% and +14% YoY growth, respectively (see exhibit 3). This sustained wave of investment underscores the ongoing build-out of large-scale data centres, AI compute clusters, and networking systems, which continues to drive structural demand across the entire electronics and automated test solutions ecosystem.

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Exhibit 5: Hyperscaler AI Chip Development and Launch Timeline (2025–2027F)

Company	Chip	1Q25	2Q25	3Q25	4Q25	1Q26	2Q26	3Q26	4Q26	1Q27	2Q27	3Q27	4Q27
Amazon	Trainium 1												
	Inferentia 2												
	Trainium 2												
	Trainium 2.5												
	Trainium 2 ultra-R2												
	Trainium 3												
	Trainium 4												
Meta	MTIA v1												
	MTIA v2												
	MTIA v3												
Google	TPU v6p												
	TPU v7e												
	TPU v7p												
MSFT	Maia 1-Athena												
	Maia 2-Braga												
	Maia 2-Griffin												
Intel	Gaudi 2												
	Gaudi 3												
Open AI	Titan 1												
	Titan 2												
xAI	X1												
Apple	Accelerator												

Source: Various news sources, Kenanga Research

Rising Demand for GPUs and Custom ASICs... At the hardware level, the AI build-out is underpinned by surging demand for GPUs (graphics processing units) and ASICs (application-specific integrated circuits) that power AI training and inference workloads. GPUs remain the dominant compute engine for large models, while ASICs are increasingly being developed by hyperscalers to optimise cost and efficiency for specific workloads (see Exhibit 5). The proliferation of these advanced processors has led to a diversification of hardware platforms, with each new generation of GPU or ASIC introducing unique board configurations and interconnect architectures. As a result, manufacturers must continually redesign and qualify AI motherboards (MLBs) and accelerator boards to accommodate the increased compute density, memory bandwidth, and power delivery requirements.

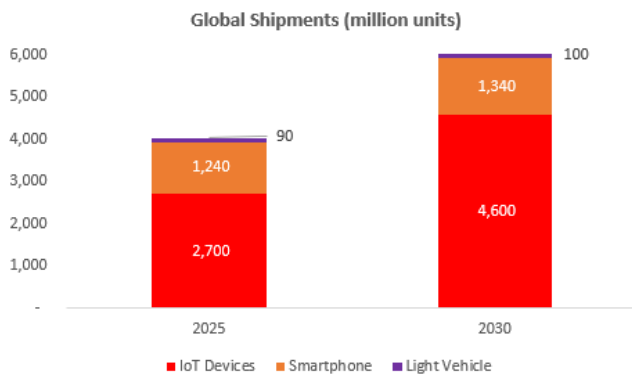
...which led to a step-change in board-level complexity. Based on our research, next-generation AI MLBs now features between 24 and 30 PCB layers, more than double the layer count of traditional server boards, and host over 200,000 test points to ensure electrical continuity and signal integrity across thousands of high-speed traces. Each board also carries an exceptionally high pin count, often exceeding 10,000 pins per unit due to the integration of multiple GPUs, memory modules, and networking interfaces. The sheer electrical and mechanical complexity of these designs demands more extensive in-circuit and functional testing to verify performance, reliability, and safety before deployment in hyperscale data centres. While Malaysia has several ICT and FCT solution providers including Hibex Malaysia, Yoshiden, Kyoritsu Electric, Circuit Check Asia, and E Xing Precision Design, most operate as foreign subsidiaries focused on standard fixtures. THMY is among the few local players with full design-to-fabrication capabilities for high-complexity test fixtures, catering to AI and datacentre applications.

Structural Implications for the Test Solutions Industry. Every incremental layer or pin added to a board multiplies the number of validation points that must be probed, leading to a sharp increase in both the volume and sophistication of test fixtures required at the manufacturing stage. At the same time, shorter design cycles and faster hardware refresh rates among hyperscalers further amplify fixture demand, as each new motherboard generation requires fresh test tooling tailored to its layout. Complementing these structural drivers, the ASEAN region, particularly Thailand, is seeing a surge in foreign investment, with nearly [60 new PCB manufacturing](#) facilities established as global producers diversify away from China amid rising geopolitical and cost pressures. Collectively, these trends establish a robust multi-year demand trajectory for the board-level test solutions industry, anchored by the sustained AI capex cycle and the escalating technical complexity of AI hardware systems.

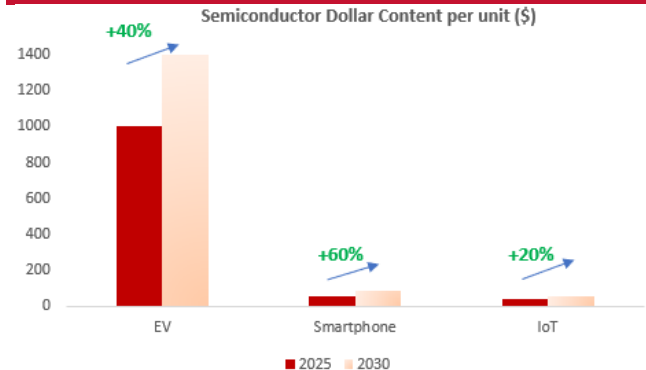
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Investment Merits

1. Secular Growth in E&E Drives Structural Test Demand

Exhibit 6: Global Demand Highlights the Broad-Based Growth Of the E&E Industry

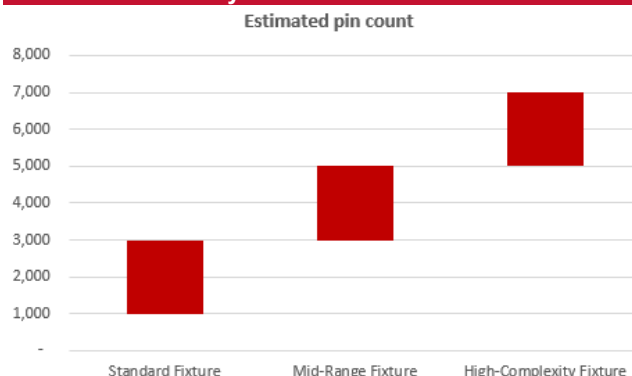
Source: Company, Kenanga Research

Exhibit 7: Rising Chip Intensity Drives Higher Semiconductor Value Per Unit

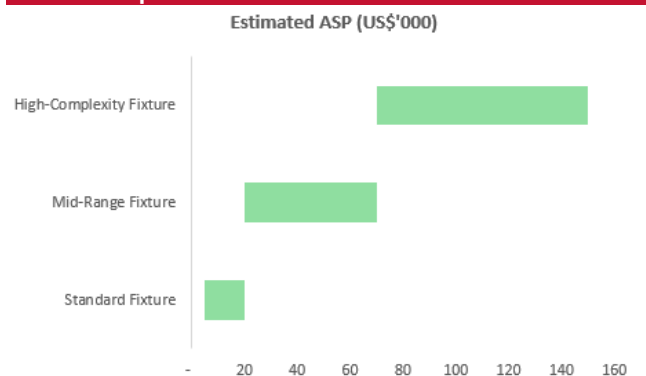
Source: Company, Kenanga Research

- Volume growth expands the testing base.** Global shipments of smartphones, IoT devices, and light vehicles are projected to rise meaningfully into 2030, reaching 4.6b, 1.34b, and 100m units, respectively (see Exhibit 6). Each of these end-products incorporates multiple PCBAs, all of which must be validated before shipment. As unit volumes grow, the base of boards requiring ICT and FCT testing also rises in tandem. For THMY, this creates a natural expansion in demand for test fixtures, as manufacturers need larger quantities of customised solutions to keep production lines running smoothly. The company benefits directly from this structural volume growth, as higher shipments translate into a steadily growing fixture order pipeline.
- Rising semiconductor content magnifies testing needs.** Importantly, growth in demand is not limited to volumes alone. The semiconductor dollar content per device is forecast to climb by 60% in smartphones, 40% in EVs, and 20% in IoT devices between 2025 and 2030 (see Exhibit 7). This reflects increasing chip intensity, where more silicon is embedded per unit to deliver higher performance, connectivity, and efficiency. More chips per unit translate into more interconnects, test points, and functional requirements that must be validated. For THMY, this raises not only the quantity of test fixtures required but also their complexity and ASPs, as denser pin counts and more sophisticated functional checks demand advanced test designs. The company is therefore positioned to benefit from both volume-driven demand and value-driven fixture upgrades, anchoring a long-term growth runway.

2. AI Server Proliferation Drives High-Complexity Testing

Exhibit 8: Higher Board Complexity Translates into Greater Pin Density in Test Fixtures.

Source: Kenanga Research

Exhibit 9: Rising Test Complexity Drives Step-Up in Fixture ASPs

Source: Kenanga Research

- Rising complexity of AI motherboards increases test fixture intensity.** The proliferation of AI servers and high-performance computing systems is driving the emergence of next-generation AI motherboards that are significantly larger and more complex than conventional server boards, designed to accommodate higher GPU density, faster memory interconnects, and networking interfaces. Each board must undergo multiple rounds of in-circuit (ICT) and functional (FCT) testing to ensure reliability, power integrity, and thermal stability before deployment in hyperscale data centres. This surge in board-level testing requirements directly increases the

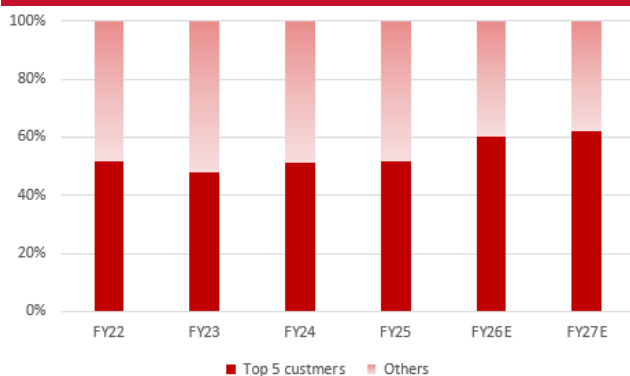
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number of high-density fixtures required per production batch, while also elevating their technical complexity and engineering value.

- **Higher pin density and validation requirements drive ASP expansion.** As pin density rises, fixture design becomes more sophisticated. A typical test fixture may involve ~1,500 contact points, with an estimated cost of ~USD5,000 and a lead time of 2-3 weeks. In contrast, fixtures designed for more complex and high-performance electronic systems can feature >6,000 contact points, requiring development cycles of up to 12–16 weeks (including software validation) and commanding meaningful higher ASPs due to increased design complexity and engineering content (see Exhibit 9). Based on a back-of-the-envelope scaling calculation, fixture ASPs tend to increase approximately tenfold as contact points quadruple, implying an average of USD120k–USD150k for high-end test solutions. Notably, for every USD10k increase in blended ASP, assuming constant shipment volume, it translates to roughly 27% upside to earnings. This shift represents a direct earnings catalyst — capturing not only higher fixture volumes from AI board proliferation but also higher margins from complexity-driven ASP uplift.

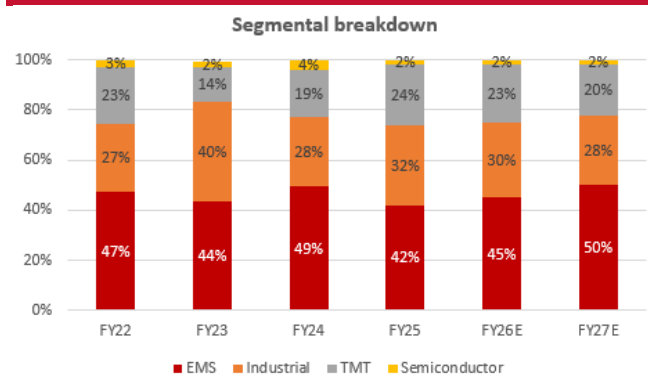
3. Established Customer Relationships Provide Structural Demand Visibility

Exhibit 10: Top 5 Customers are Expected to Contribute 60/62% of Revenue in FY26/FY27



Source: Company, Kenanga Research

Exhibit 11: EMS Remains THMY's Largest Revenue Contributor



Source: Company, Kenanga Research

- **Proven Track Record Serving MNCs.** THMY has built a strong and diversified customer base comprising leading electronics manufacturing services (EMS) providers, as well as major players in the industrial and technology, media, and telecommunications (TMT) sectors. Notably, the top five customers contributed 51% of total revenue in FY25 (see Exhibit 10). These customers operate across a broad spectrum of applications, from industrial automation and instrumentation to networking infrastructure and consumer electronics — all of which are experiencing increasing testing requirements as products become more compact, connected, and performance-driven. Through years of collaboration, THMY has established strong stickiness with its key customers, who rely on the Group for dependable, customised ICT and FCT solutions validated across multiple product generations.
- **Strategic Exposure to Hyperscaler-Linked Supply Chains.** Several of THMY's key customers operate as tier-one EMS and module suppliers to major global hyperscalers, producing PCB assemblies and integrated boards used in AI, cloud, and high-performance computing systems. As these hyperscalers continue expanding their data-centre and AI infrastructure, their contract manufacturers are scaling production of increasingly complex, multi-layered boards with each requiring rigorous in-circuit and functional validation before shipment. This testing demand naturally cascades down to THMY, which provides the customised test fixtures and automation solutions needed at the board validation stage. The company's close working relationships with these manufacturing partners give it indirect yet recurring exposure to the fast-growing AI hardware cycle.

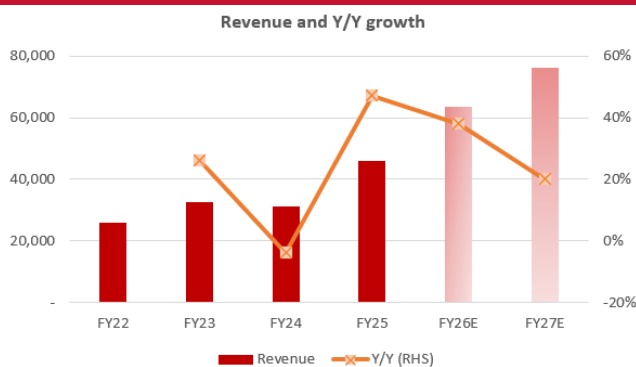
Financial Highlights

Financial review. The Group recorded steady growth in both revenue and profitability over the financial years under review. Revenue increased from approximately RM25.8m in FY22 to RM31.2m in FY24, representing a two-year CAGR of about 10%, before rising sharply by 47.1% to RM45.9m in FY25 (see Exhibit 12). The overall improvement in revenue was mainly driven by higher contributions from ICT solutions, supported by the post-pandemic recovery in manufacturing activities and the onboarding of new OEM customers from the technology, media and telecommunications sectors. In addition, higher sales to key customers such as Test Solution Co. Ltd, Customer A, Customer H and Customer I also contributed to the strong top-line performance. Profitability strengthened in tandem with revenue growth. Profit after tax (PAT) rose from RM1.3m in FY22 to RM10.0m in FY25, representing a three-year CAGR of approximately 108% (see Exhibit 13). The improvement was mainly

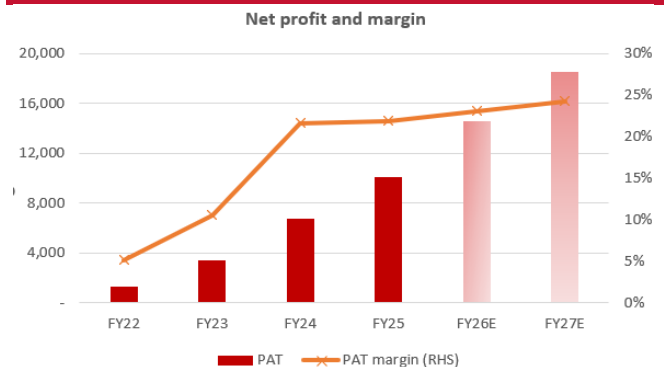
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due to higher gross profit stemming from increased revenue, better cost control, and favourable sales mix. The Group's gross profit margin expanded from 21.4% in FY22 to 41.2% in FY25, reflecting enhanced operational efficiency and economies of scale.

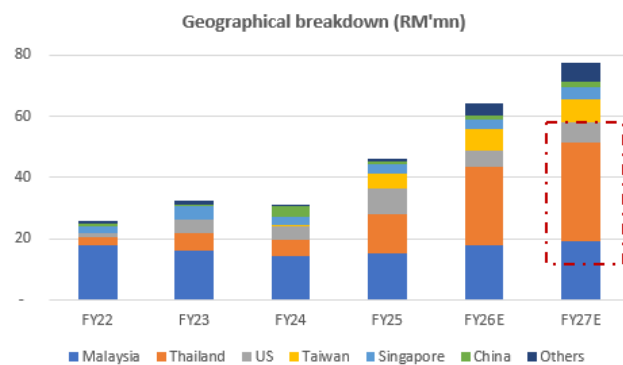
Financial forecasts. We forecast its revenue to grow 40%/21% YoY in FY26/FY27, driven by strong demand from EMS customers in Thailand, which is rapidly emerging as a regional hub for PCB production (see Exhibit 14). This shift positions Thailand as a key beneficiary of the global supply chain realignment, creating a structural growth tailwind for THMY as it supports increasing test requirements from new PCB capacity expansion. Notably, gross profit margin is expected to improve to 45%/47% in FY26/FY27, supported by a greater mix of complex, high-value fixtures that command higher ASPs and stronger cost leverage. Consequently, PAT is projected to grow by 48%/26% in FY26/FY27, with margins expanding to 23%/24%, driven by the mix shift towards high-complexity fixtures, the high-ASP segment is expected to rise to around 10% of total shipments by FY26 (from ~6% currently), which command stronger margins due to higher engineering content and customisation value. Looking ahead, THMY plans to commission a new factory by 2QCY29, designed to house 20 FCT assembly workstations, compared to five currently at its Batu Kawan facility. This expansion will quadruple the Group's FCT solution capacity, providing a clear runway for medium-term growth and scalability.

Exhibit 12: Revenue and Growth


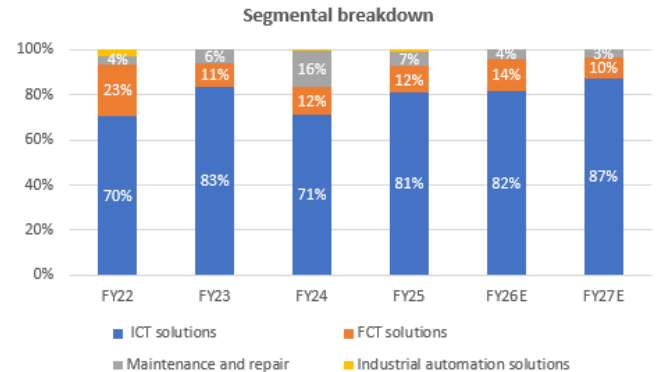
Source: Company, Kenanga Research

Exhibit 13: Net Profit and Margin


Source: Company, Kenanga Research

Exhibit 14: Increasing Contribution from Thailand-Driven EMS Demand


Source: Company, Kenanga Research

Exhibit 15: ICT is Expected to Remain the Main Revenue Contributor


Source: Company, Kenanga Research

Valuation

We assign a fair value of RM0.60 to THMY, based on 30x CY26F EPS, representing a ~20% discount to both regional and local peers and a ~35% discount to Malaysia-listed peers in the automated test and semiconductor equipment space. The applied discount reflects THMY's relatively smaller market capitalisation and lower earnings base, though we expect this gap to narrow as the company scales up its operations and improves profitability. Despite the discount, we view THMY's valuation as attractive given its structural growth visibility, supported by rising demand from EMS customers in Thailand, expanding exposure to hyperscaler-linked production, and a growing proportion of high-complexity, higher-margin fixtures. The Group's plan to quadruple its FCT assembly capacity by 2QCY29 further reinforces its medium-term growth trajectory. As THMY continues to demonstrate execution strength and deepen its role within the AI and high-performance computing supply chain, we see potential for a progressive re-rating towards peer multiples.

Exhibit 16: Comparison of Local and Regional Peers in the Industry

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Company	Country	Ticker	Market Cap. (RM m)	Revenue (RM m)	Net Margin	1-yr Average Fwd PER (x)
Malaysia						
Vitrox	Malaysia	VITRO MK	8,254.5	552.3	16%	65.1
Pentamaster	Malaysia	PENT MK	3,044.4	623.0	10%	42.9
MI Technovation	Malaysia	MI MK	2,589.4	463.5	15%	30.3
Aimflex	Malaysia	AIMFLEX MK	145.3	78.6	11%	-
Regional						
Chroma	Taiwan	2360 TT	39,566.8	3,074.9	24%	35.1
Beijing Huafeng Test & Control	China	688200 CH	16,238.8	575.2	38%	58.3
Bojay Electronics	China	002975 CH	5,510.6	783.2	2%	20.7
Kyoritsu Electronic Corp	Japan	6874 JP	585.2	1,125.6	6%	15.7
Simple Average			9,491.9	909.5	15%	38.3
THMY			275.3	45.9	22%	30.0

Source: Bloomberg, Kenanga Research

Key risks include: (i) high customer concentration among major EMS clients, (ii) slower-than-expected adoption of high-complexity test solutions, and (iii) cyclical slowdown in global electronics and hyperscaler capex.

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Income Statement

FYE May (RM m)	2023A	2024A	2025A	2026F	2027F
Revenue	32.5	31.2	45.9	64.1	77.4
EBITDA	5.3	9.0	12.1	21.3	28.1
Depreciation	0.9	0.9	1.7	4.0	4.9
Operating Profit	4.5	8.1	10.4	17.3	23.2
Other Income	0.8	1.3	0.2	-	-
Interest Exp	(0.1)	(0.1)	(0.2)	(0.3)	(0.3)
Associate	-	-	-	-	-
Exceptional Items	-	-	-	-	-
PBT	4.5	8.5	10.6	17.0	22.9
Taxation	(1.1)	(1.7)	(0.6)	(2.2)	(4.2)
Minority Interest	-	-	-	-	-
Net Profit	3.4	6.8	10.0	14.8	18.7
Core Net Profit	3.4	6.8	10.0	14.8	18.7

Balance Sheet

FYE May (RM m)	2023A	2024A	2025A	2026F	2027F
Fixed Assets	4.5	9.5	23.5	39.8	48.6
Intangible Assets	0.4	0.8	0.8	0.8	0.8
Other FA	0.1	-	-	-	-
Inventories	0.9	3.7	7.6	7.9	9.5
Receivables	11.9	8.5	11.1	15.8	19.1
Other CA	0.1	0.2	4.9	4.9	4.9
Cash	9.2	10.5	2.2	33.1	41.3
Total Assets	27.2	33.1	50.3	102.4	124.2
Payables	7.3	7.4	7.8	11.2	13.5
ST Borrowings	0.2	1.1	2.7	2.7	2.7
Other ST Liability	6.3	9.4	11.6	11.6	11.6
LT Borrowings	2.2	2.1	9.6	4.4	4.4
Other LT Liability	0.2	0.2	0.7	0.7	0.7
Minorities Int.	-	-	-	-	-
Net Assets	11.1	12.9	17.9	71.9	91.4
Share Capital	-	-	16.4	56.2	56.2
Reserves	10.1	11.9	16.9	31.7	50.4
Equity	11.1	12.9	17.9	71.9	91.4

Cashflow Statement

FYE May (RM m)	2023A	2024A	2025F	2026F	2027F
Operating CF	4.0	6.4	4.5	13.2	16.9
Investing CF	(8.3)	(9.7)	(7.8)	(16.3)	(8.7)
Financing CF	2.0	0.4	4.3	34.8	-

Financial Data & Ratios

FYE May	2023A	2024A	2025A	2026F	2027F
Growth (%)					
Turnover	26.1	-3.9	47.1	39.6	20.7
EBITDA	65.2	69.8	33.5	76.5	31.8
Operating Profit	86.6	81.1	28.4	66.7	34.1
PBT	88.3	89.0	25.5	59.6	34.7
Net Profit	159.8	96.5	48.8	47.6	25.8
Core Net Profit	159.8	96.5	48.8	47.6	25.8
Profitability (%)					
EBITDA Margin	16.4	28.9	26.3	33.2	36.3
Operating Margin	13.7	25.9	22.6	27.0	30.0
PBT Margin	13.8	27.2	23.2	26.5	29.6
Core Net Margin	10.6	21.6	21.9	23.1	24.1
Effective Tax Rate	23.5	20.4	5.7	12.8	18.6
ROA	12.6	20.4	20.0	14.5	15.0
ROE	30.9	52.5	56.1	20.4	20.5
DuPont Analysis					
Net Margin (%)	10.6	21.6	21.9	23.1	24.1
Assets Turnover (x)	1.4	1.0	1.1	0.8	0.7
Leverage Factor (x)	2.4	2.5	2.7	1.7	1.4
ROE (%)	30.9	52.5	56.1	20.4	20.5
Leverage					
Debt/Asset (x)	0.09	0.10	0.24	0.07	0.05
Debt/Equity (x)	0.21	0.25	0.69	0.10	0.08
Net (Cash)/Debt	6.9	7.3	(10.0)	34.2	44.8
Net Debt/Equity (x)	0.62	0.57	(0.56)	0.36	0.38
Valuations					
Core EPS (sen)	0.4	0.8	1.1	1.7	2.1
NDPS (sen)	0.0	0.0	0.0	0.0	0.0
BVPS (RM)	0.01	0.01	0.02	0.08	0.10
Core PER (x)	79.5	40.8	27.4	18.6	14.8
Net Div. Yield (%)	0.0	0.0	0.0	0.0	0.0
P/BV (x)	24.8	21.4	15.4	3.8	3.0

Source: Kenanga Research

22 October 2025

Stock Ratings are defined as follows:**Stock Recommendations**

OUTPERFORM	: A particular stock's Expected Total Return is MORE than 10%
MARKET PERFORM	: A particular stock's Expected Total Return is WITHIN the range of -5% to 10%
UNDERPERFORM	: A particular stock's Expected Total Return is LESS than -5%

Sector Recommendations***

OVERWEIGHT	: A particular sector's Expected Total Return is MORE than 10%
NEUTRAL	: A particular sector's Expected Total Return is WITHIN the range of -5% to 10%
UNDERWEIGHT	: A particular sector's Expected Total Return is LESS than -5%

*****Sector recommendations are defined based on market capitalisation weighted average expected total return for stocks under our coverage.**

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Published by:

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